

SN54LS377, SN54LS378, SN54LS379, SN74LS377, SN74LS378, SN74LS379

OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

SDLS167 – OCTOBER 1976 – REVISED MARCH 1988

- 'LS377 and 'LS378 Contain Eight and Six Flip-Flops, Respectively, with Single-Rail Outputs
- 'LS379 Contains Four Flip-Flops with Double-Rail Outputs
- Individual Data Input to Each Flip-Flop
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators

description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic with an enable input. The 'LS377, 'LS378, and 'LS379 devices are similar to 'LS273, 'LS174, and 'LS175, respectively, but feature a common enable instead of a common clear.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the enable input \bar{G} is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at the \bar{G} input.

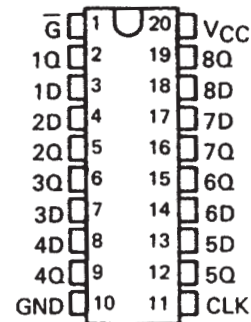
These flip-flops are guaranteed to respond to clock frequencies ranging from 0 to 30 MHz while maximum clock frequency is typically 40 megahertz. Typical power dissipation is 10 milliwatts per flip-flop.

FUNCTION TABLE
(EACH FLIP-FLOP)

INPUTS			OUTPUTS	
\bar{G}	CLOCK	DATA	Q	\bar{Q}
H	X	X	Q_0	\bar{Q}_0
L	↑	H	H	L
L	↑	L	L	H
X	L	X	Q_0	\bar{Q}_0

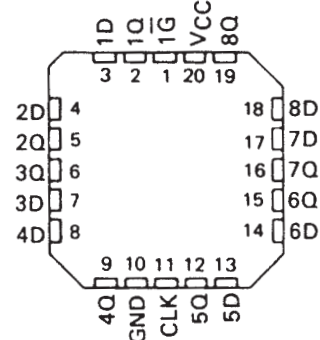
SN54LS377 . . . J PACKAGE
SN74LS377 . . . DW OR N PACKAGE

(TOP VIEW)



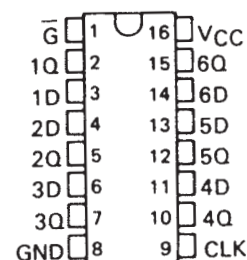
SN54LS377 . . . FK PACKAGE

(TOP VIEW)



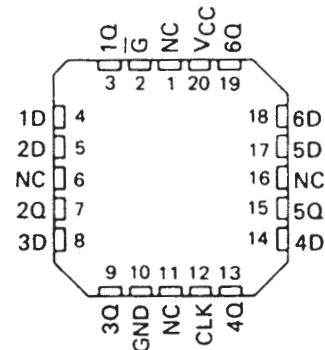
SN54LS378 . . . J OR W PACKAGE
SN74LS378 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS378 . . . FK PACKAGE

(TOP VIEW)

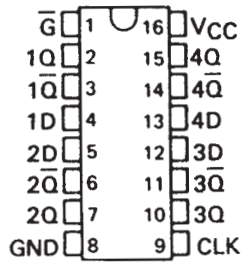


NC – No internal connection

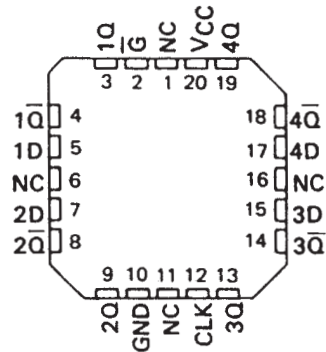
SN54LS377, SN54LS378, SN54LS379, SN74LS377, SN74LS378, SN74LS379 OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

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SN54LS379 . . . J OR W PACKAGE
SN74LS379 . . . D OR N PACKAGE
(TOP VIEW)

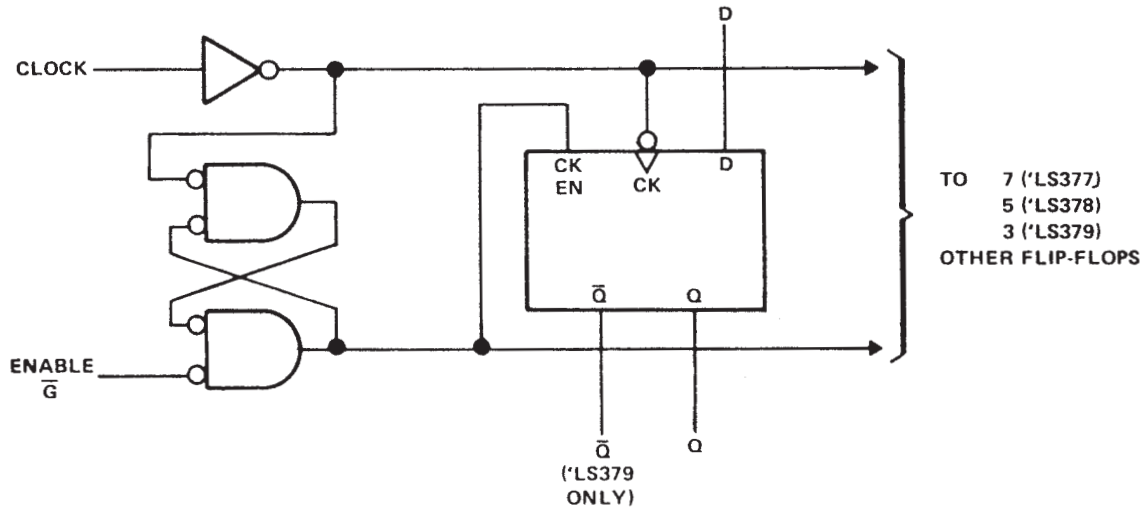


SN54LS379 . . . FK PACKAGE
(TOP VIEW)

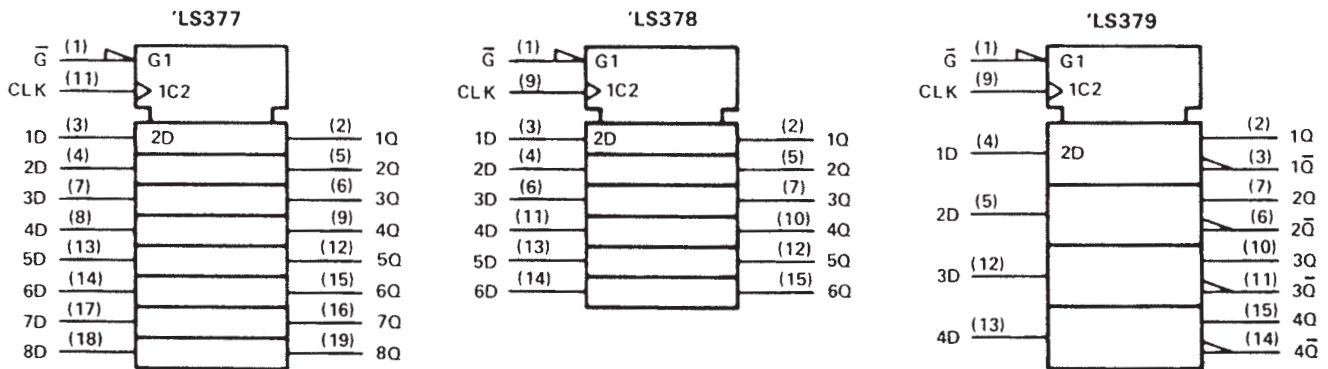


NC – No internal connection

logic diagram (positive logic)



logic symbols†

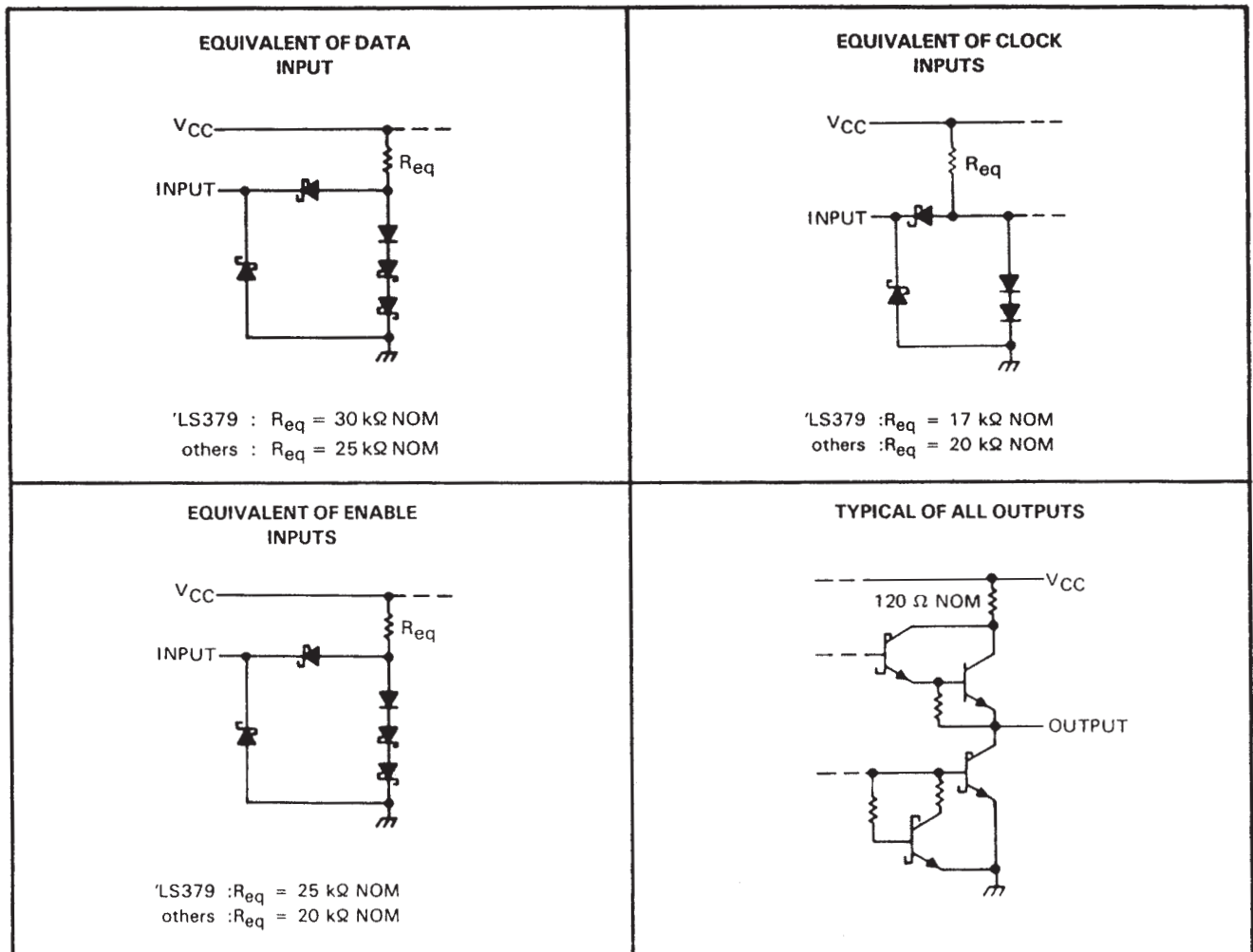


† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, and N packages.

SN54LS377, SN54LS378, SN54LS379,
SN74LS377, SN74LS378, SN74LS379
OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

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schematics of inputs and outputs



absolute maximum rating over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage	7 V
Operating free-air temperature range: SN54LS'	-55°C to 125°C
SN74LS'	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

SN54LS377, SN54LS378, SN54LS379, SN74LS377, SN74LS378, SN74LS379 OCTAL, HEX, AND QUAD D-TYPE FLIP-FLOPS WITH ENABLE

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recommended operating conditions

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-400			-400	μ A
Low-level output current, I_{OL}			4			8	mA
Clock frequency, f_{clock}	0		30	0		30	MHz
Width of clock pulse, t_W	20			20			ns
Setup time, t_{su}	Data input	20†		20†			ns
	Enable active-state	25†		25†			
	Enable inactive-state	10†		10†			
Hold time, t_h	Data and enable	5†		5†			ns
Operating free-air temperature, T_A	-55		125	0		70	$^{\circ}$ C

† The arrow indicates that the rising edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54LS'			SN74LS'			UNIT	
		MIN	TYP‡	MAX	MIN	TYP‡	MAX		
V_{IH} High-level input voltage		2			2			V	
V_{IL} Low-level input voltage				0.7			0.8	V	
V_{IK} Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$			-1.5			-1.5	V	
V_{OH} High-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$ $V_{IL} = V_{IL \text{ max}}, I_{OH} = -400 \mu\text{A}$	2.5	3.5		2.7	3.5		V	
V_{OL} Low-level output voltage	$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V},$ $V_{IL} = V_{IL \text{ max}}$			0.25	0.4		0.25	0.4	V
	$I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$						0.35	0.5	
I_I Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$			0.1			0.1	mA	
I_{IH} High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$			20			20	μ A	
I_{IL} Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$			-0.4			-0.4	mA	
I_{OS} Short-circuit output current§	$V_{CC} = \text{MAX}$	-20		-100	-20		-100	mA	
I_{CC} Supply current	$V_{CC} = \text{MAX},$ See Note 2	'LS377	17	28	17	28	mA		
		'LS378	13	22	13	22	mA		
		'LS379	9	15	9	15	mA		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$.

§ Note more than one input should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and ground applied to all data and enable inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max} Maximum clock frequency	$C_L = 15 \text{ pF},$	30	40		MHz
t_{PLH} Propagation delay time, low-to-high-level output from clock	$R_L = 2 \text{ k}\Omega$		17	27	ns
t_{PHL} Propagation delay time, high-to-low-level output from clock	See Note 3		18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-8992501EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8992501FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8992501FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/32504B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/32504B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/32504BRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
JM38510/32504BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SN54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74LS377DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS377N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS377N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS377N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS377NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS377NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS377NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS377NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74LS377NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS378N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS378N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS378N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS378NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS378NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS378NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS378NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS379D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS379D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS379J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS379J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS379N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS379N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS377FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS377FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS377J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS377W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS377W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ54LS378FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS378FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS378J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS378W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS378W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS379FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS379FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS379J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS379W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS379W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

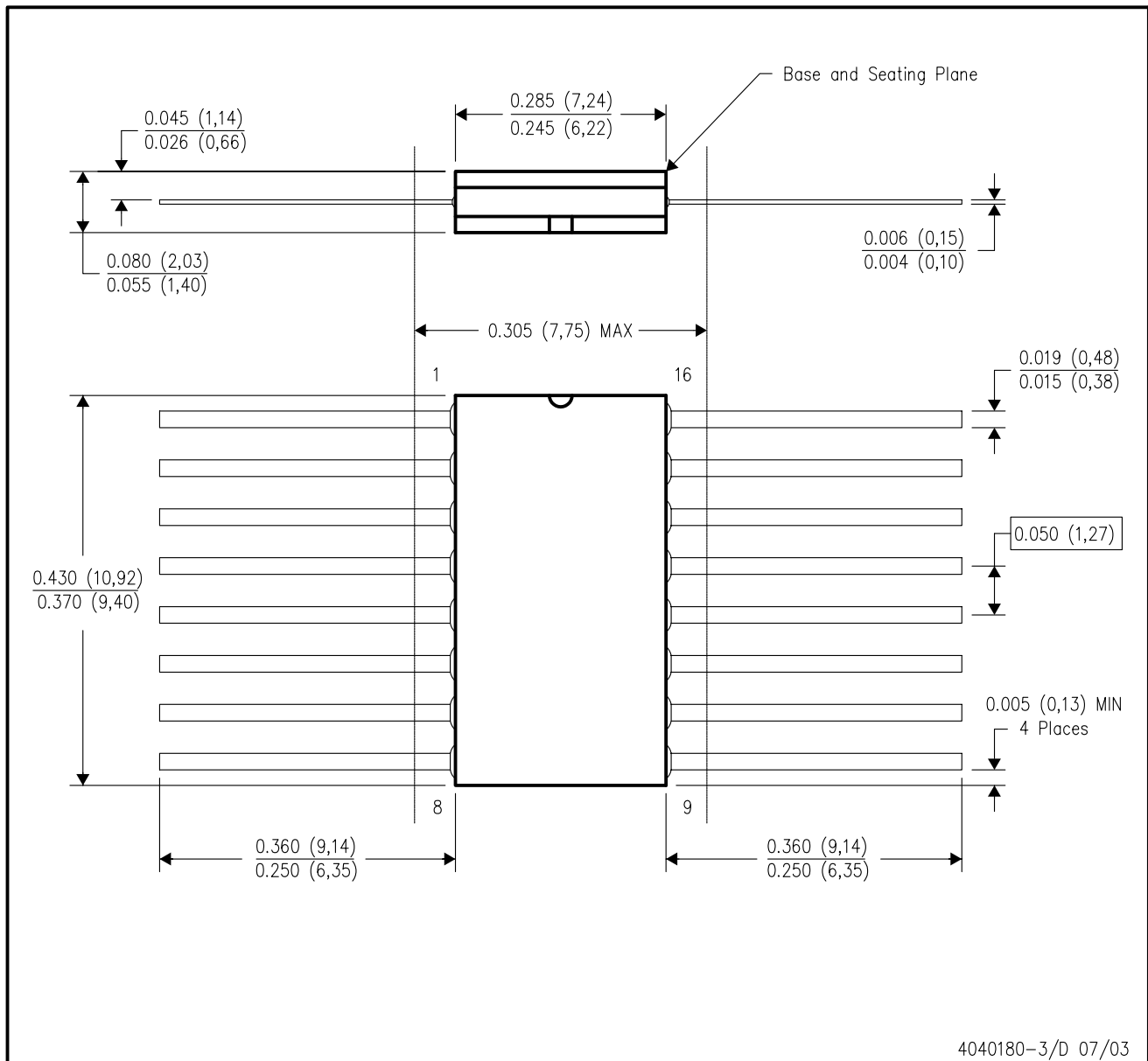


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

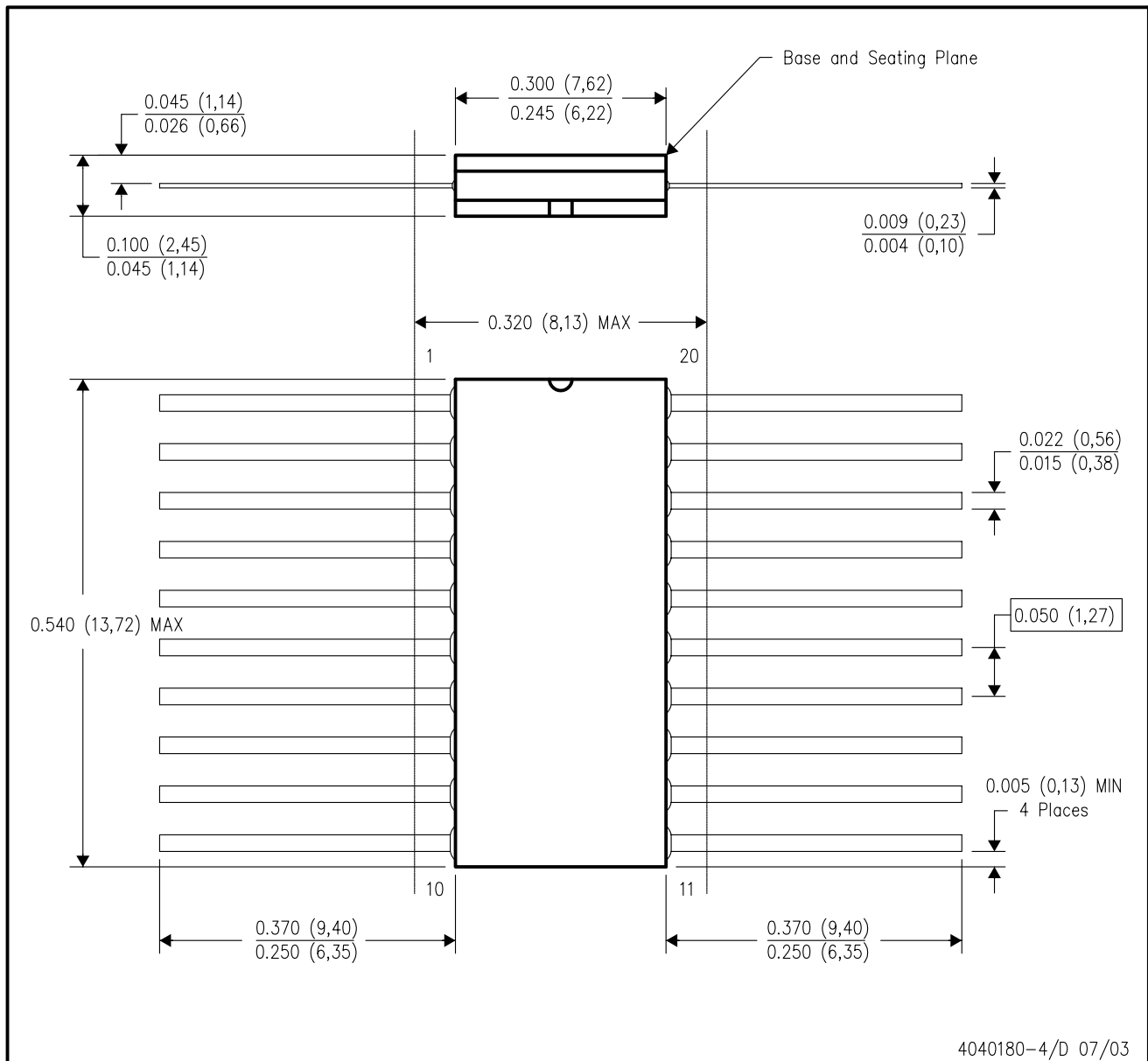
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

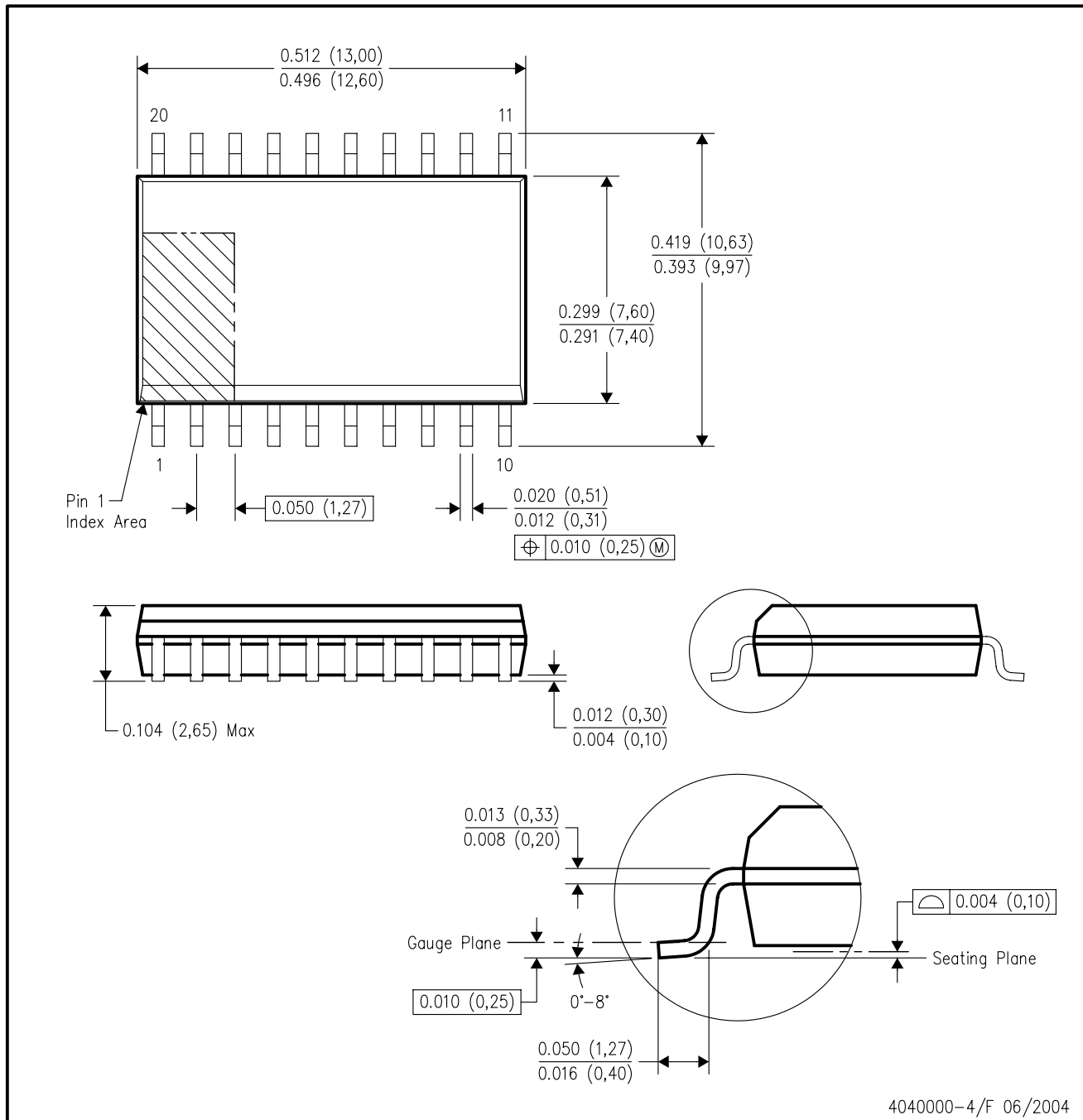
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

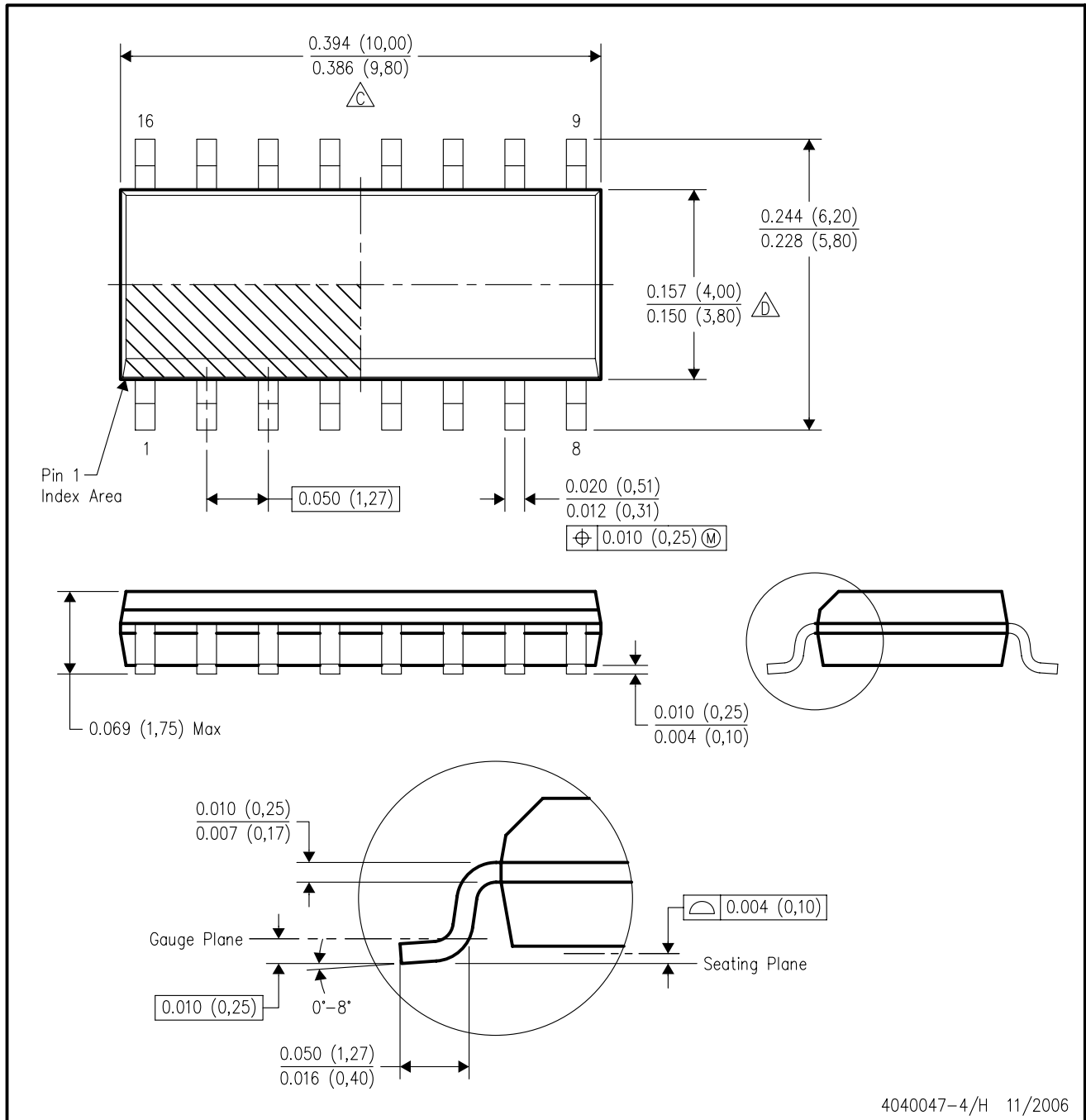
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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